

Title (en)

METHOD, DEVICE AND INSTALLATION FOR PRODUCING PRINTED CIRCUIT BOARDS

Title (de)

VERFAHREN, VORRICHTUNG UND ANLAGE ZUR LEITERPLATTENHERSTELLUNG

Title (fr)

PROCÉDÉ, DISPOSITIF ET INSTALLATION DE FABRICATION DE CARTES DE CIRCUITS IMPRIMÉS

Publication

**EP 3659408 A1 20200603 (DE)**

Application

**EP 18740745 A 20180629**

Priority

- DE 102017212887 A 20170726
- EP 2018067715 W 20180629

Abstract (en)

[origin: WO2019020318A1] In a method for producing printed circuit boards, a substrate (112), which has a carrier layer made of an electrically insulating material and an electrically conductive layer applied thereto, is processed in a plurality of steps. To carry out a development step and/or an etching step, the substrate (112) is rotated. A developer solution and/or an etching liquid is applied to the rotating substrate (112) by means of at least one nozzle (113). In addition to the method, a device suitable for carrying out the method and an installation comprising the device are described.

IPC 8 full level

**H05K 3/06** (2006.01)

CPC (source: EP KR US)

**H01L 21/6708** (2013.01 - US); **H05K 3/064** (2013.01 - KR US); **H05K 3/068** (2013.01 - EP KR US); **H05K 3/064** (2013.01 - EP); **H05K 2203/0165** (2013.01 - EP KR US); **H05K 2203/0169** (2013.01 - EP KR US); **H05K 2203/075** (2013.01 - EP KR US); **H05K 2203/1509** (2013.01 - EP KR US); **H05K 2203/1554** (2013.01 - EP KR US); **H05K 2203/1572** (2013.01 - EP KR US)

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**WO 2019020318 A1 20190131**; CN 111133846 A 20200508; DE 102017212887 A1 20190131; EP 3659408 A1 20200603; JP 2020528219 A 20200917; JP 2023182826 A 20231226; JP 7438100 B2 20240226; KR 102674414 B1 20240611; KR 20200030111 A 20200319; KR 20230156815 A 20231114; TW 201922073 A 20190601; TW I783015 B 20221111; US 11963306 B2 20240416; US 2020221579 A1 20200709; US 2024155773 A1 20240509

DOCDB simple family (application)

**EP 2018067715 W 20180629**; CN 201880062667 A 20180629; DE 102017212887 A 20170726; EP 18740745 A 20180629; JP 2020504129 A 20180629; JP 2023182557 A 20231024; KR 20207005543 A 20180629; KR 20237038491 A 20180629; TW 107125814 A 20180726; US 201816633840 A 20180629; US 202418415774 A 20240118